

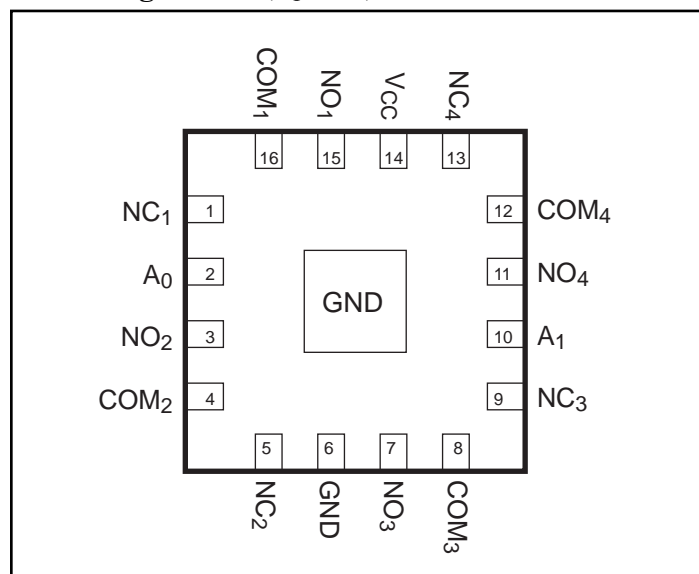
Features

- CMOS Technology for Bus and Analog Applications
- Low On-Resistance: 0.4Ω (+2.7V Supply)
- Wide V_{CC} Range: +1.6V to +4.2V
- I_{CC} = 0.3μA @ T_A = +25°C
- Rail-to-Rail switching throughout Signal Range
- Fast Switching Speed: 20ns TYP. at 3.3V
- High Off Isolation: -65dB
- Crosstalk Rejection: -65dB
- Extended Industrial Temperature Range: -40°C to 85°C
- Packaging: (Pb-free & Green)
 - 16-contact TQFN (ZL), 2.5mm x 2.5mm
 - 16-contact TQFN (ZH), 3.0mm x 3.0mm

Applications

- Cell Phones
- PDAs
- Portable Instrumentation
- Battery Powered Communications
- Computer Peripherals
- Audio & Video Signal Routing
- PCMCIA Cards
- Modems
- Hard Drives
- JTAG Testing

Pin Configuration (top view)

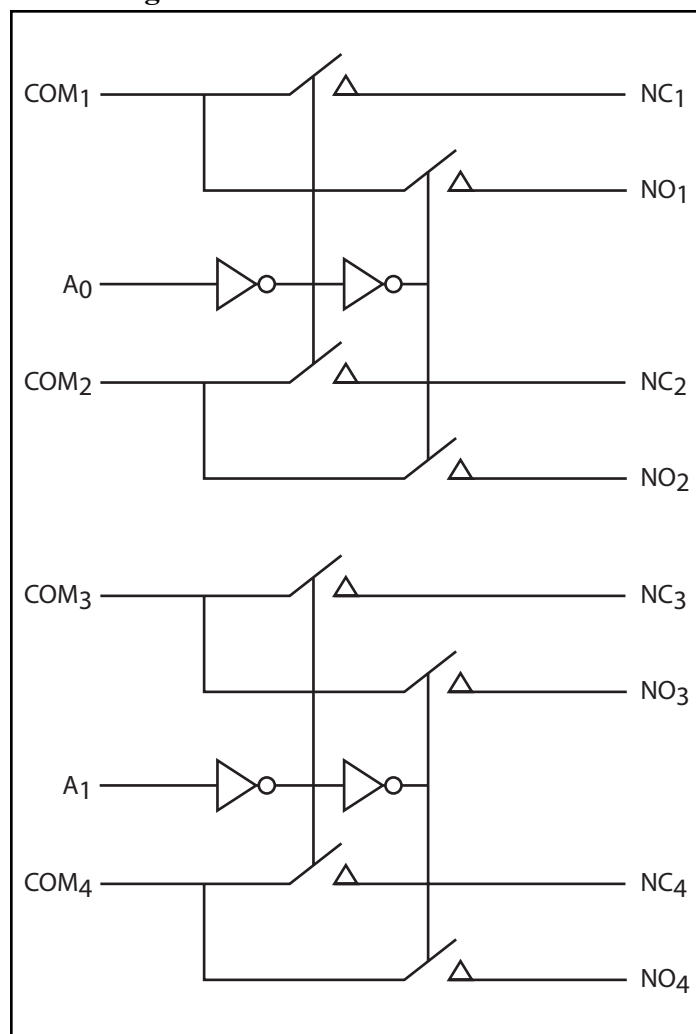


Description

The PI3A412 is a quad single-pole double-throw (SPDT) CMOS switch. It can be used as an analog switch or as a low-delay bus switch. Specified over a wide operating power supply voltage range, +1.6V to +4.2V, the switch has an On-Resistance of 0.4Ω at 2.7V.

Control inputs, A_x, tolerates input drive signals up to 5V, independent of supply voltage.

Block Diagram



Pin Description

Pin #	Name	Description
4, 8, 12, 16	COM _X	Common Output / Data Port
1, 5, 9, 13	NC _X	Data Port (normally connect)
3, 7, 11, 15	NO _X	Data Port (normally open)
2, 10	A ₀ , A ₁	Logic Input Control
6	GND	Ground
14	V _{CC}	Positive Power Supply

Notes :

1. X = 1, 2, 3, or 4

Function Tables

A ₀	Function	A ₁	Function
0	NC _X Connected to COM _X	0	NC _Y Connected to COM _Y
1	NO _X Connected to COM _X	1	NO _Y Connected to COM _Y

Notes :

1. X = 1 or 2
-
2. Y = 3 or 4

Absolute Maximum Ratings

Voltages Referenced to GND

V_{CC} 1.5V to +4.6V

V_{NOx}, V_{NCx}, V_{COMx}, V_{Ax} ⁽¹⁾ -0.5V to V₊ +0.3V
or 30mA, whichever occurs first

Current (any terminal)..... ±400mA

Peak Current, V_{NC} + V_{NO}
(Pulsed at 1ms, 10% duty cycle)..... ±500mA

Thermal Information

Continuous Power Dissipation

16-pin Thin QFN (derate 7.1mW/°C above +70°C)..... 0.5W

Storage Temperature -65°C to +150°C

Lead Temperature (soldering, 10s) +300°C

Note 1: Signals on NC, NO, COM, or A exceeding V_{CC} or GND are clamped by internal diodes. Limit forward diode current to 30mA.

Caution: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied.

Electrical Specifications - Single +3.3V Supply
 $(V_{CC} = +3.3V \pm 10\%, GND = 0V, V_{IH} = 1.3V, V_{IL} = 0.5V) (T_A = -40^\circ C \text{ to } +85^\circ C)$

Parameter	Symbol	Conditions	Min. ⁽¹⁾	Typ. ⁽²⁾	Max. ⁽¹⁾	Units
Analog Signal Range ⁽³⁾	V_{ANALOG}		0		V_{CC}	V
On Resistance	R_{ON}	$V_{CC} = 2.7V, I_{COM} = 100mA, V_{IN} = +1.5V$		0.4	0.6	Ω
On-Resistance Match Between Channels ⁽⁴⁾	ΔR_{ON}			0.08	0.09	
On-Resistance Flatness ⁽⁵⁾	$R_{FLAT(ON)}$			0.1	0.15	
Off Leakage Current ⁽⁶⁾	$I_{NC} \text{ (off)}$ or $I_{NO} \text{ (off)}$	$V_{CC} = 3.6V$ $V_{NO} \text{ or } V_{NC} = 0.3V, 3.3V$	-400		400	nA
On Leakage Current ⁽⁶⁾	$I_{COMx} \text{ (on)}$	$V_{CC} = 3.6V,$ $V_{COMx} = 0.3V, 3.3V$	-400		400	

Notes:

1. The algebraic convention, where most negative value is a minimum and most positive is a maximum, is used in this data sheet.
2. Typical values are $T_A = 25^\circ C$, $V_{CC} = 3.3V$ unless otherwise specified.
3. Guaranteed by design.
4. $\Delta R_{ON} = R_{ON}$ match between channels
5. Flatness is defined as the difference between the maximum and minimum value of On-Resistance measured.
6. Leakage parameters are 100% tested at maximum rated hot temperature and guaranteed by correlation at $+25^\circ C$.

Electrical Specifications - Single +4.2V Supply
 $(V_{CC} = +4.2V, GND = 0V, V_{IH} = 1.6V, V_{IL} = 0.7V) (T_A = -40^\circ C \text{ to } +85^\circ C)$

Parameter	Symbol	Conditions	Min. ⁽¹⁾	Typ. ⁽²⁾	Max. ⁽¹⁾	Units
Analog Signal Range ⁽³⁾	V_{ANALOG}		0		V_{CC}	V
On Resistance	R_{ON}	$V_{CC} = 4.0V, I_{COMx} = 100mA, V_{IN} = +1.5V$		0.4	0.6	Ω
On-Resistance Match Between Channels ⁽⁴⁾	ΔR_{ON}			0.08	0.09	
On-Resistance Flatness ⁽⁵⁾	$R_{FLAT(ON)}$			0.1	0.15	
Off Leakage Current ⁽⁶⁾	$I_{NC} \text{ (off)}$ or $I_{NO} \text{ (off)}$	$V_{CC} = 4.2V,$ $V_{NO} \text{ or } V_{NC} = 0.3V, 3.3V$	-500		500	nA
On Leakage Current ⁽⁶⁾	$I_{COMx} \text{ (on)}$	$V_{CC} = 4.2V,$ $V_{COMx} = 0.3V, 3.3V$	-500		500	

Notes:

1. The algebraic convention, where most negative value is a minimum and most positive is a maximum, is used in this data sheet.
2. Typical values are $T_A = 25^\circ C$, $V_{CC} = 4.2V$ unless otherwise specified.
3. Guaranteed by design.
4. $\Delta R_{ON} = R_{ON}$ match between channels
5. Flatness is defined as the difference between the maximum and minimum value of On-Resistance measured.
6. Leakage parameters are 100% tested at maximum rated hot temperature and guaranteed by correlation at $+25^\circ C$.

Electrical Specifications - Single +4.2V Supply
 $(V_{CC} = +4.2V, GND = 0V, V_{IH} = 1.6V, V_{IL} = 0.7V) (T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

Description	Parameter	Test Conditions	Min. ⁽¹⁾	Typ. ⁽²⁾	Max. ⁽¹⁾	Unit
Logic Input						
Input High Voltage	V _{IH}	Guaranteed logic High Level	1.6			V
Input Low Voltage	V _{IL}	Guaranteed logic Low Level			0.7	
Input Current with Voltage High	I _{AH}	V _A = 1.4V, all others = 0.5V	−1		1	μA
Input Current with Voltage Low	I _{AL}	V _A = 0.5V, all other = 1.4V	−1		1	
Dynamic						
Turn-On Time	t _{ON}	V _{CC} = 4.2V, V _{COM} = 2.0V, Figure 1 & 2		20	25	ns
Turn-Off Time	t _{OFF}			12	15	
Break-Before-Make	t _{BBM}	V _{IN} = 1.5V, R _L = 50Ω, C _L = 35pF, See Figure 3	1	12	15	
Charge Injection ⁽³⁾	Q	C _L = 1nF, V _{GEN} = 0V, R _{GEN} = 0Ω, Figure 4		100		pC
Off Isolation ⁽⁴⁾	O _{IRR}	R _L = 50Ω, f = 100kHz, Figure 5		-65		dB
Cross Talk ⁽⁵⁾	X _{TALK}	R _L = 50Ω, f = 100kHz, Figure 6		-65		
3dB Bandwidth	f _{3db}	See Test Circuit Figure 9		40		MHz
Off Capacitance	C _{N(COFF)}	f = 1 MHz, Figure 7		50		pF
Off Capacitance	C _{N(OFF)}			50		
On Capacitance	C _{ON}	f = 1 MHz, Figure 8		135		
Supply						
Power-Supply Range	V _{CC}		1.5		4.4	V
Positive Supply Current	I _{CC}	V _{CC} = 4.2V, V _A = 0V or V _{CC}			1.5	μA

Notes:

1. The algebraic convention, where most negative value is a minimum and most positive is a maximum, is used in this data sheet.
2. Typical values are $T_A = 25^{\circ}C$, $V_{CC} = 4.2V$ unless otherwise specified.
3. Guaranteed by design.
4. Off Isolation = $20\log_{10} [(V_{NO} \text{ or } V_{NC}) / V_{COM}]$. See Figure 5.
5. Between any two switches. See Figure 6.

Electrical Specifications - Single +3.3V Supply

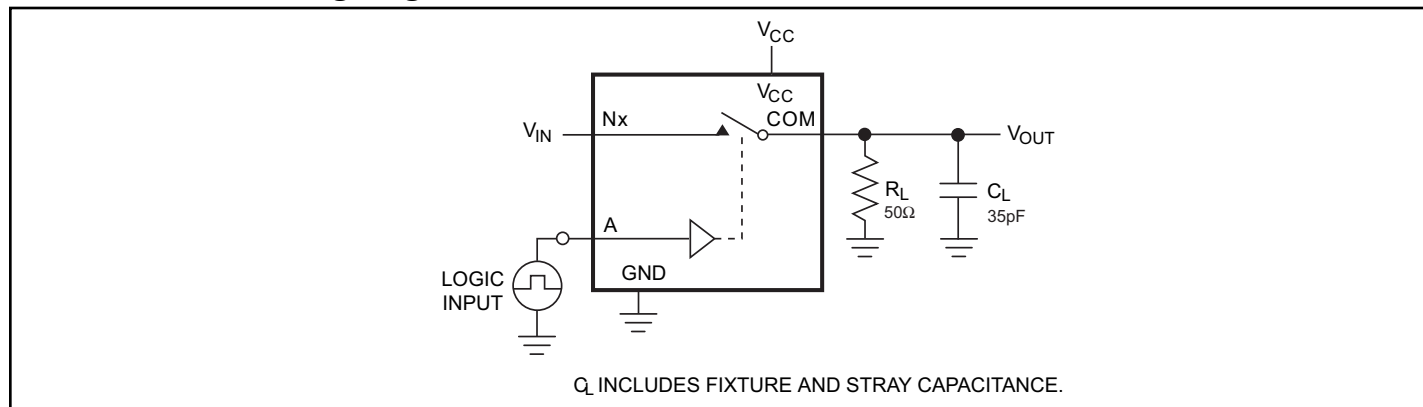
($V_{CC} = +3.3V \pm 10\%$, $GND = 0V$, $V_{IH} = 1.3V$, $V_{IL} = 0.5V$) ($T_A = -40^\circ C$ to $+85^\circ C$)

Description	Param- eters	Test Conditions	Min. ⁽¹⁾	Typ. ⁽²⁾	Max. ⁽¹⁾	Units
Logic Input						
Input High Voltage	V _{IH}	Guaranteed logic High Level	1.3			V
Input Low Voltage	V _{IL}	Guaranteed logic Low Level			0.5	
Input Current with Voltage High	I _{AH}	V _A = 1.4V, all others = 0.5V	−1		1	μA
Input Current with Voltage Low	I _{AL}	V _A = 0.5V, all other = 1.4V	−1		1	
Dynamic						
Turn-On Time	t _{ON}	V _{CC} = 3.3V, V _{COM} = 2.0V, Figure 1 & 2		20	25	ns
Turn-Off Time	t _{OFF}			12	15	
Break-Before-Make	t _{BBM}	V _{IN} = 1.5V, R _L = 50Ω, C _L = 35pF, See Figure 3	1	12	15	
Charge Injection ⁽³⁾	Q	C _L = 1nF, V _{GEN} = 0V, R _{GEN} = 0Ω, Figure 4		100		pC
Off Isolation ⁽⁴⁾	O _{IRR}	R _L = 50Ω, f = 100kHz, Figure 5		-65		dB
Cross Talk ⁽⁵⁾	X _{TALK}	R _L = 50Ω, f = 100kHz, Figure 6		-65		
3dB Bandwidth	f _{3db}	See Test Circiut Figure 9		40		MHz
Off Capacitance	C _{NC(OFF)}	f = 1 MHz, Figure 7		50		pF
Off Capacitance	C _{NO(OFF)}			50		
On Capacitance	C _{ON}	f = 1 MHz, Figure 8		135		

Notes:

1. The algebraic convention, where most negative value is a minimum and most positive is a maximum, is used in this data sheet.
2. Typical values are $V_{CC} = 3.3V$ unless otherwise specified.
3. Guaranteed by design.
4. Off Isolation = $20\log_{10} [(V_{NO} \text{ or } V_{NC}) / V_{COM}]$. See Figure 5.
5. Between any two switches. See Figure 6.

Test Circuits and Timing Diagrams



Notes:

Unused N_X inputs must be grounded.

Figure 1. AC Test Circuit

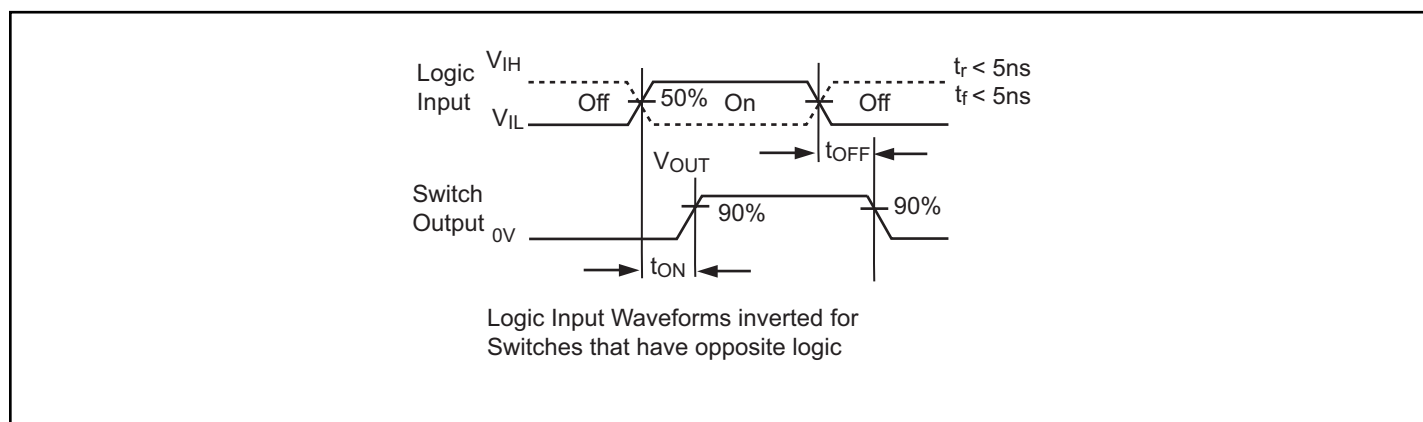


Figure 2. AC Waveforms

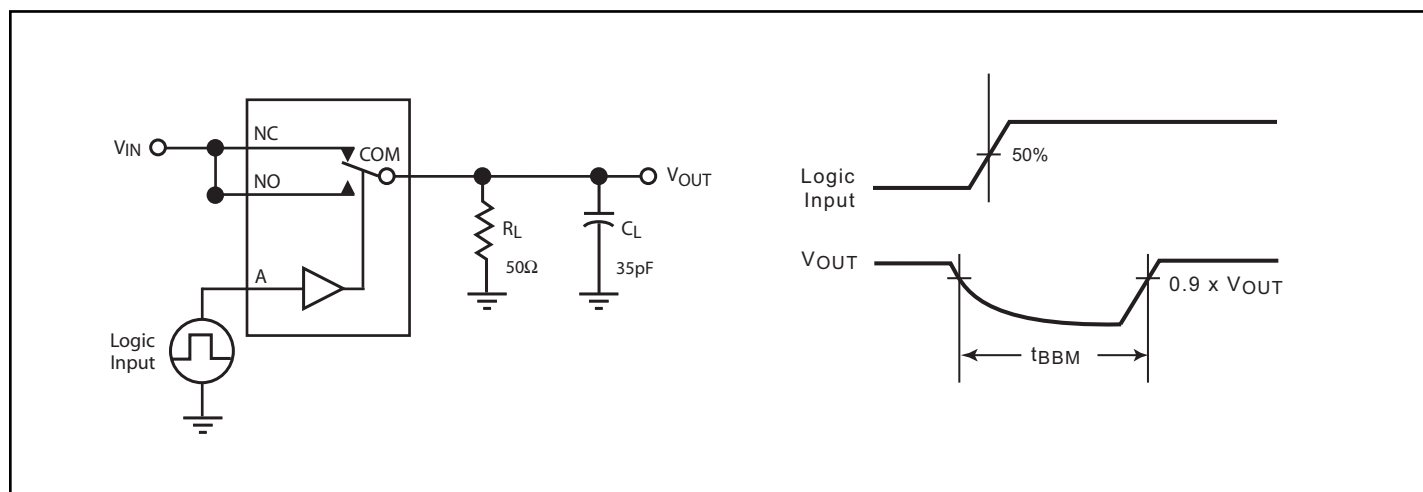


Figure 3. Break Before Make Interval Timing

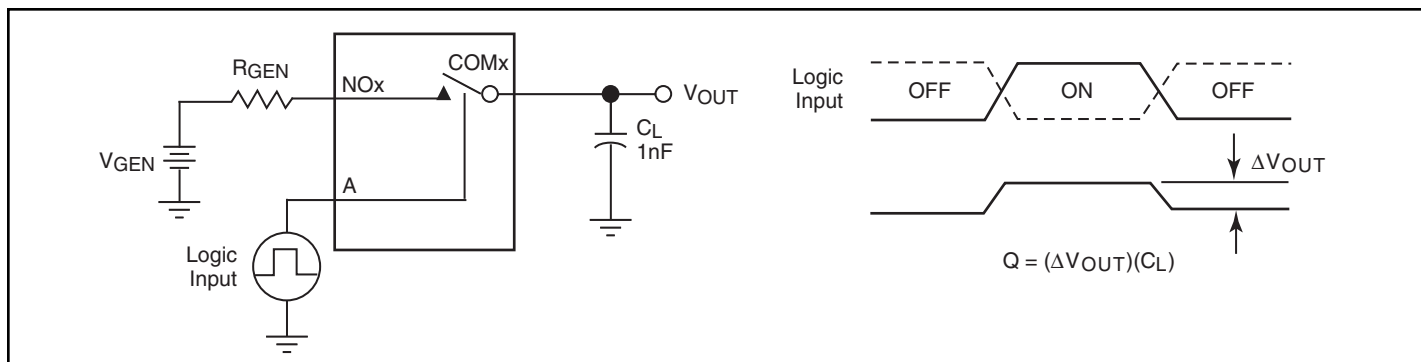


Figure 4. Charge Injection Test

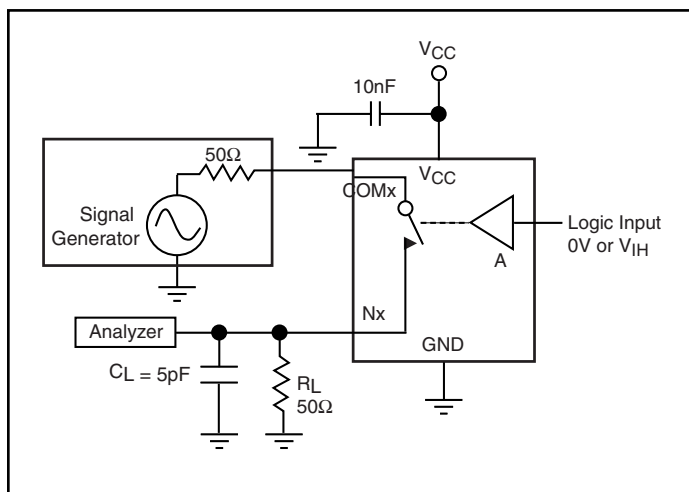


Figure 5. Off Isolation

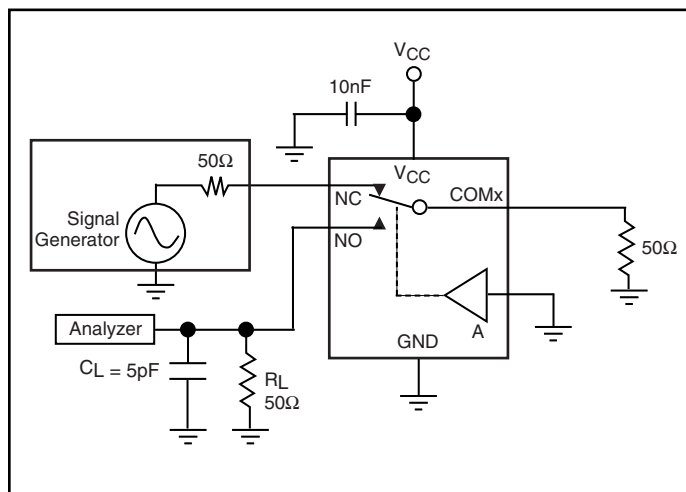


Figure 6. Crosstalk

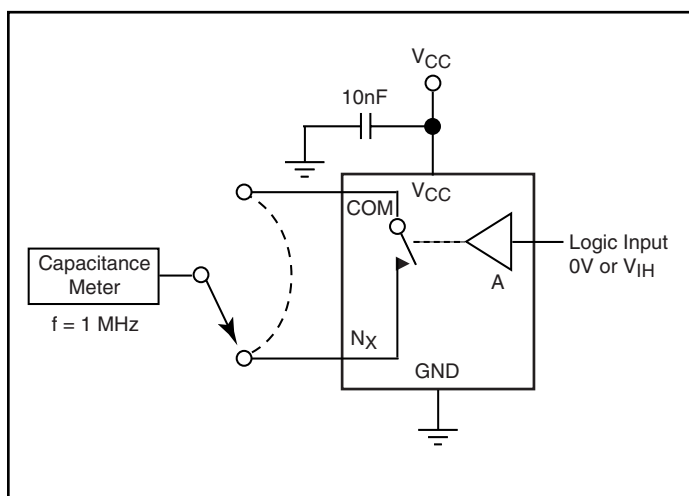


Figure 7. Channel Off Capacitance

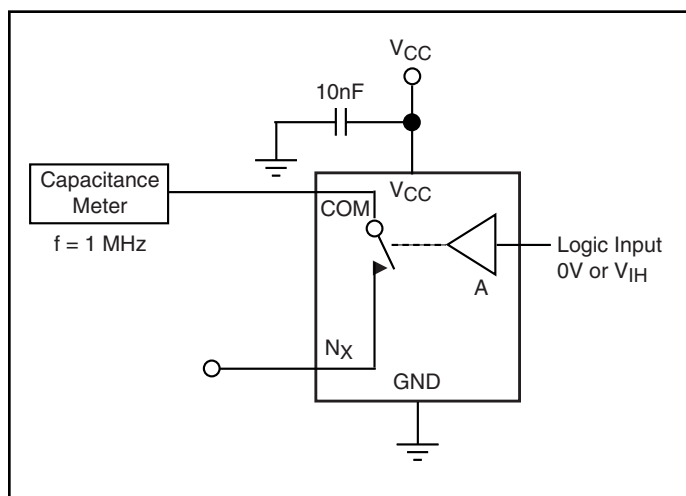


Figure 8. Channel On Capacitance

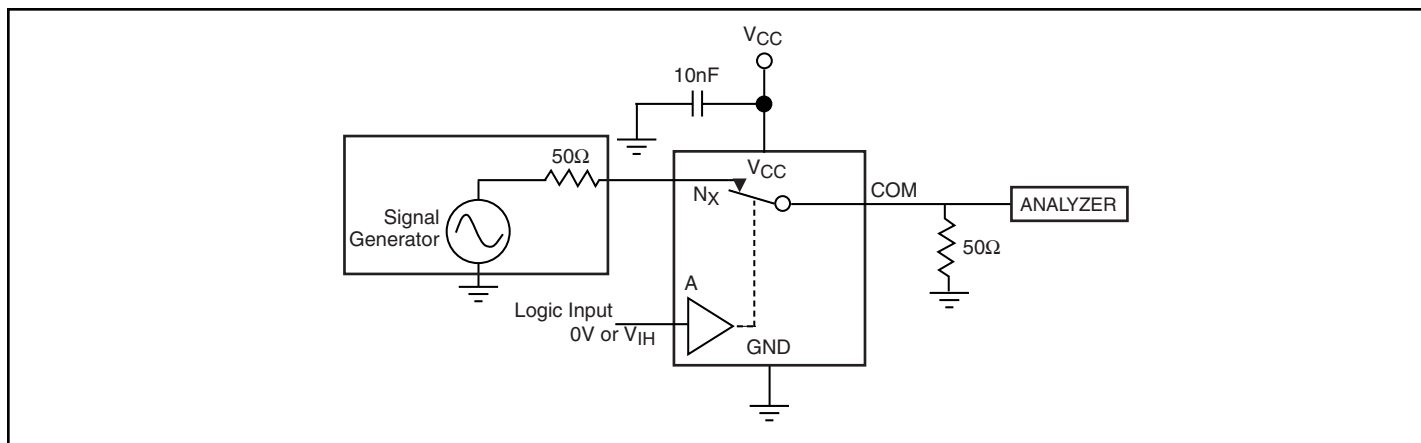
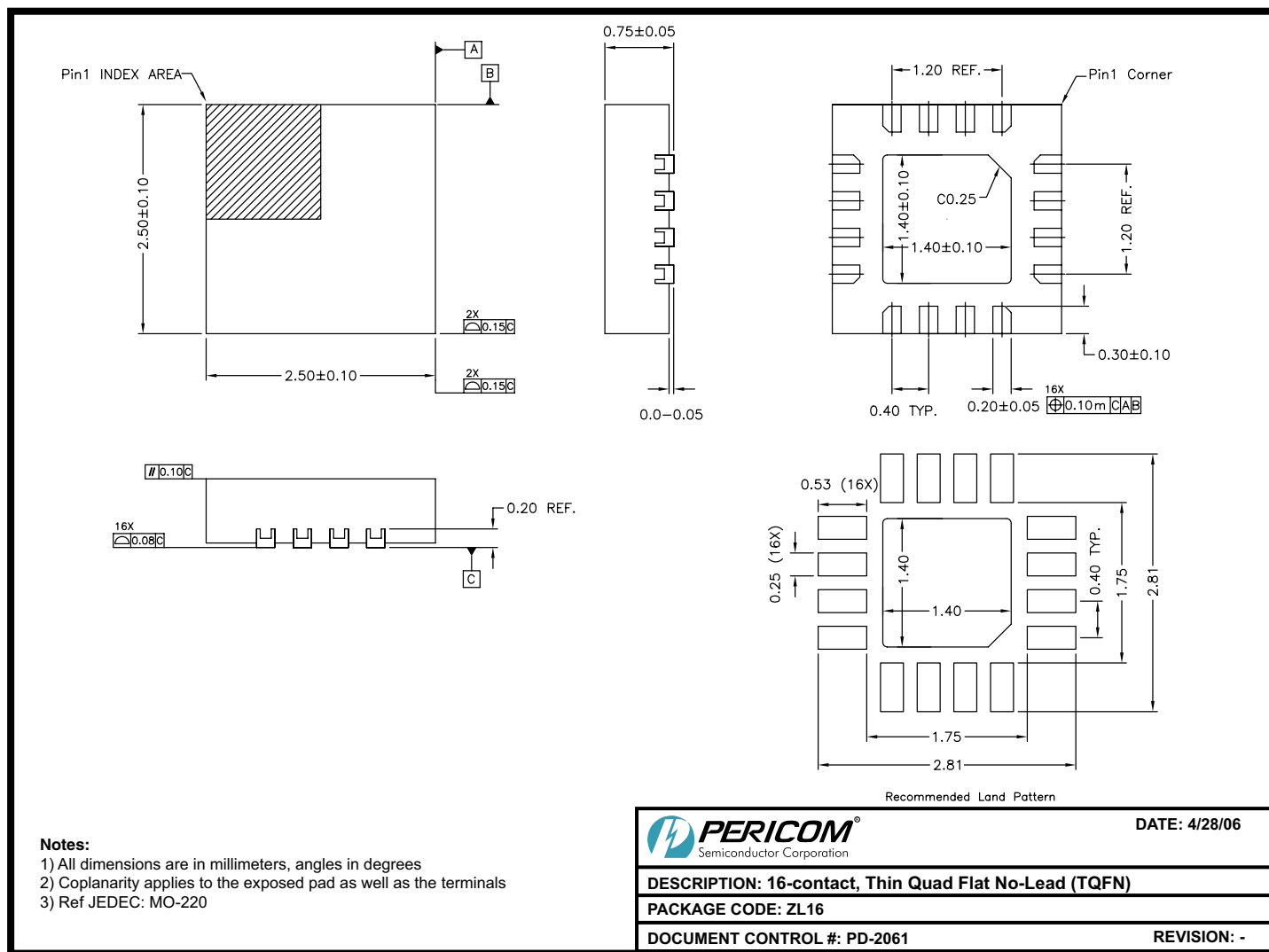
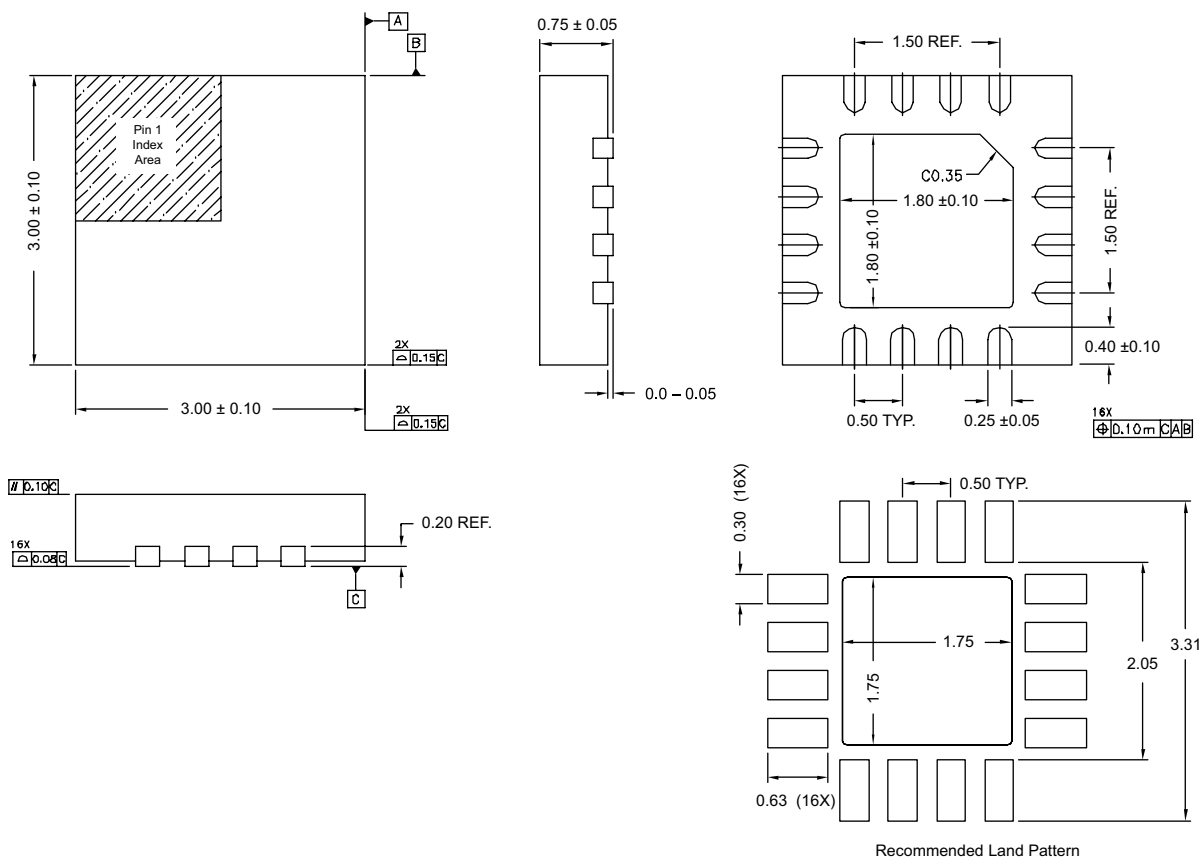


Figure 9. Bandwidth




Notes:

- 1) All dimensions are in millimeters
- 2) Ref JEDEC: MO-220J (WEED)
- 3) Bilateral coplanarity zone applies to the exposed heat sink slug as well as the terminals


DATE: 03/16/06
DESCRIPTION: 16-Contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)
PACKAGE CODE: ZH (ZH16)
DOCUMENT CONTROL #: PD-2047
REVISION: A

Ordering Information

Ordering Code	Package Code	Package Description
PI3A412ZLE	ZL	Pb-free & Green, 16-contact TQFN
PI3A412ZHE	ZH	Pb-free & Green, 16-contact TQFN

Notes:

- Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
- E = Lead-free and Green Packaging
- Adding X suffix = Tape/Reel